

EL979953748

Inventor: Kyle K. Kirby; Shuang Meng; and Garo J. Derderian

Title: Methods of Fabricating Interconnects for Semiconductor Components

Assignee: Micron Technology, Inc.

INFORMATION DISCLOSURE STATEMENT

References – See Attached Form PTO-1449

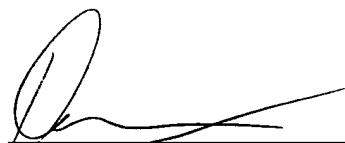
The attached form PTO-1449 is submitted in compliance with 37 CFR § 1.56. Copies of the cited art are included with the exception of U.S. patents and published U.S. applications (1276 OG 55). No admission is made regarding whether all the submitted references are prior art.

Respectfully submitted,

Dated: _____

2/20/04

By: _____



David G. Latwesen, Ph.D.
Reg. No. 38,533

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-2401		SERIAL NO. Filed Herewith	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Micron Technology, Inc.			
				FILING DATE Filed herewith		GROUP Unknown	

U.S. PATENT DOCUMENTS							
*Examiner Initial	Document Number	Date	Name	Class	Subclasses	Filing Date If Appropriate	
	AA	6,107,109	Akram et al.				
	AB	6,114,240	Akram et al.				
	AC	6,294,837	Akram et al.				
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclasses	Translation	
						Yes	No
	AK						
	AL						

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)			
	AM		Electroless Plating; http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm ; 12/5/2003; pp. 1-4
	AN		Electroless Plating; http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm ; 10/20/2003; pp. 1-2
	AO		Slide Show: "Through-Water Copper Electroplating for RF Silicon Technology"; N.T. Nguyen et al.; DIMES - TU Delft, Netherlands; http://www.essderc2002.deis.unibo.it/ESSDERC_web/Session_D11/D11_2.pdf
	AP		"Atomic Layer Deposition of TiN Films by Alternate Supply of Tetrakis(ethylmethylamino)-Titanium and Ammonia" ; Jae-Sik Min, Young-Woong Son, et al.; Jpn. J. Appl. Phys. Vol. 37 (1998) pp. 4999-5004; Part 1, No. 9A; September 1998 Japanese Journal of Applied Physics

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							Yes	No
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	AL							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AM		"Kinetic modeling of film growth rates of TiN films in atomic layer deposition", Jung-Wook Lim et al., Journal of Applied Physics; Vol. 87, No. 9; 1 May 2000; pp. 4632-4634					
	AN							
	AO							
	AP							
EXAMINER				DATE CONSIDERED				
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